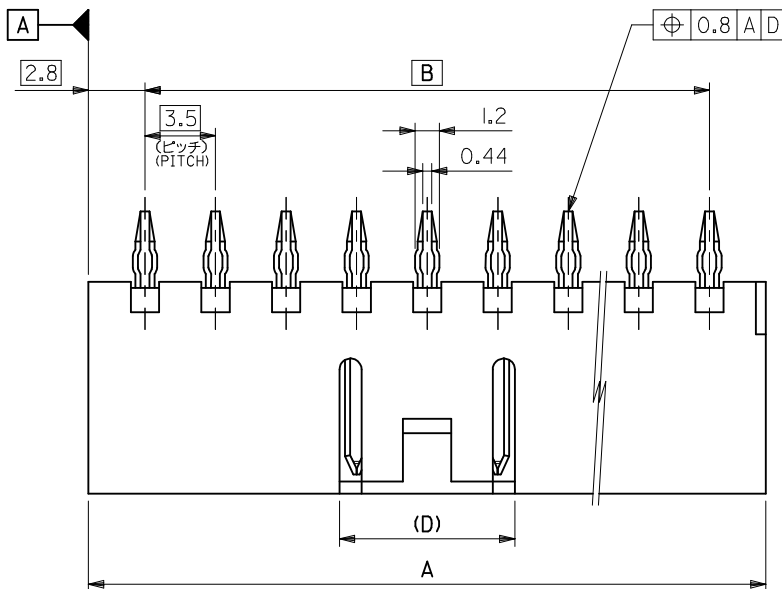
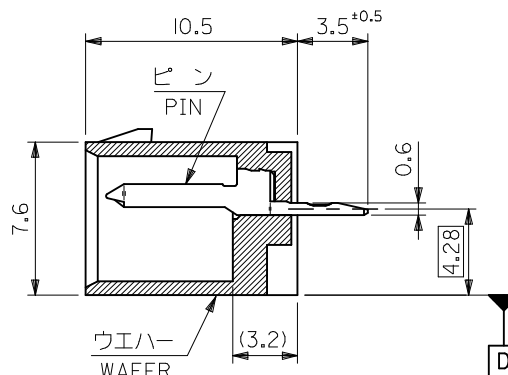
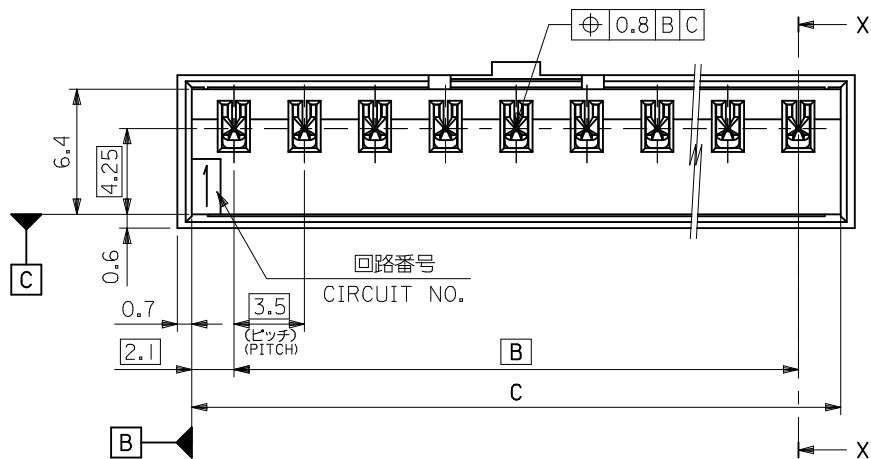


注記 NOTES

1. 嵌合相手 : 51067 シリーズ
MATE WITH : 51067 SERIES
2. 材質
MATERIAL
ウエハー : PBTP (ガラス15%入り) 、UL94V-0
WAFER : PBTP (G.F. 15%) , UL94V-0
ピン : 黄銅、ニッケル下地 鍍メッキ (t=0.254)
PIN : BRASS
TIN OVER NICKEL PLATING (t=0.254)
3. 本製品は 53258-**-20 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53258-**-20.
4. メッキ仕様
TERMINAL PLATING
表面メッキ : スズメッキ 1μm MIN.
SURFACE PLATE : TIN 1μm MIN.
下地メッキ : ニッケルメッキ 1μm MIN.
UNDER PLATE : NICKEL 1μm MIN.

基板取付穴推奨寸法 (参考) (t=1.6)
RECOMMENDED P.C. BOARD HOLE DIM. (REF.)



SECT-X-X

8.7	53.2	49.0	54.6	53258-1529	15
49.7	45.5	51.1	-1429	14	
46.2	42.0	47.6	-1329	13	
42.7	38.5	44.1	-1229	12	
39.2	35.0	40.6	-1129	11	
35.7	31.5	37.1	-1029	10	
32.2	28.0	33.6	-0929	9	
28.7	24.5	30.1	-0829	8	
25.2	21.0	26.6	-0729	7	
21.7	17.5	23.1	-0629	6	
18.2	14.0	19.6	-0529	5	
8.7	14.7	10.5	16.1	-0429	4
6.1	11.2	7.0	12.6	-0329	3
6.1	7.7	3.5	9.1	53258-0229	2
(D)	C	B	A	MATERIAL NO.	CKT. 極致

MODEL NO. 53258-**-29

REVISED EC NO.: J2007-0432 DWG/KS1 T001 CHKD: THARUYAWA APPR: NUKITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY T. UENO		DATE 2004/04/22	TITLE 3.5 WIRE TO BOARD CONN -LEAD FREE-			
		10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO		DATE 2004/04/22				
		30 OVER	± 0.3	APPROVED BY M. SASAO		DATE 2004/04/22				
		ANGULAR ±3 °		MATERIAL NO.		MOLEX MOLEX INCORPORATED				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART						DOCUMENT NO. SD-53258-005
		REV A				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

MATERIAL
材料注記参照
SEE NOTES